

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT3283451

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	TAKESHI KISHIDA	03/24/2015
<b>RECEIVING PARTY DATA</b>		
<b>Name:</b>	MICRON TECHNOLOGY, INC.	
<b>Street Address:</b>	MS 1-525	
<b>Internal Address:</b>	8000 SOUTH FEDERAL WAY	
<b>City:</b>	BOISE	
<b>State/Country:</b>	IDAHO	
<b>Postal Code:</b>	83716	
<b>PROPERTY NUMBERS Total: 1</b>		
	<b>Property Type</b>	<b>Number</b>
	Application Number:	14663878
<b>CORRESPONDENCE DATA</b>		
<b>Fax Number:</b>	(509)838-3424	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
<b>Phone:</b>	509-624-4276	
<b>Email:</b>	docketing@wellsstjohn.com	
<b>Correspondent Name:</b>	MARK S. MATKIN	
<b>Address Line 1:</b>	WELLS ST. JOHN P.S.	
<b>Address Line 2:</b>	601 W. 1ST AVE., #1300	
<b>Address Line 4:</b>	SPOKANE, WASHINGTON 99201	
<b>ATTORNEY DOCKET NUMBER:</b>	MI22-5738	
<b>NAME OF SUBMITTER:</b>	MARK S. MATKIN	
<b>SIGNATURE:</b>	/Mark S. Matkin/	
<b>DATE SIGNED:</b>	03/26/2015	
<b>Total Attachments: 3</b>		
source=Assignment#page1.tif		
source=Assignment#page2.tif		
source=Assignment#page3.tif		

## **ASSIGNMENT**

### **PARTIES TO THE ASSIGNMENT:**

#### **INVENTOR:**

Takeshi KISHIDA  
c/o Micron Memory Japan, Inc., 2-1,  
Yaesu 2-chome, Chuo-ku,  
Tokyo, Japan

#### **ASSIGNEE:**

Micron Technology, Inc. .  
MS 1-525  
8000 South Federal Way  
Boise, ID 83716  
United States

### **BACKGROUND OF THIS ASSIGNMENT:**

Inventor has conceived certain new and useful inventions disclosed in a United States patent application titled Semiconductor Memory Devices Including Support Film Supporting Capacitor Electrodes, having U.S. Patent Application Serial No. 14/663878, which was filed March 20, 2015.

Micron Technology, Inc. (hereinafter referred to as "ASSIGNEE") desires to acquire the entire right, title and interest in said inventions and with respect to any Letters Patent that may be granted with respect to the inventions in both the United States and in all foreign countries.

### **THE PARTIES AGREE AS FOLLOWS:**

In consideration of good and valuable consideration, the receipt, sufficiency and adequacy of which is hereby acknowledged, INVENTOR has sold, assigned and transferred, and by these present do hereby sell, assign

and transfer to ASSIGNEE the entire right, title and interest in the above-identified inventions and application and to any reissues, renewals, divisions or continuations of the application thereof, and hereby authorizes the Commissioner of Patents and Trademarks to issue such Letters Patent to ASSIGNEE for the sole use of ASSIGNEE, its successors or assigns.

INVENTOR further agrees to execute, at the request and expense of ASSIGNEE, such other formal documents as may be required to fully convey the interest transferred herein and will similarly execute any patent application papers (foreign or domestic) required for the filing of any divisional, continuation, renewal or reissue of the patent application or resulting Letters Patent; and will generally do everything necessary or desirable to obtain and enforce proper protection for the inventions assigned hereby.

INVENTOR further assigns to ASSIGNEE the whole right, title and interest in the inventions disclosed in the application throughout all countries foreign to the United States. ASSIGNEE is hereby authorized to apply for patents relating to the inventions in its own name in countries where such procedure is proper; to claim the benefit of the International Convention; to file and prosecute International Applications relating to the inventions under the Patent Cooperation Treaty; and to file and prosecute applications relating to the inventions under the European Patent Convention. INVENTOR agrees to execute applications relating to the inventions in those countries and under those conventions where it is necessary that the same be executed by the inventor, and to execute assignments of such applications and the resulting Letters Patent to ASSIGNEE as well as all other necessary papers in relation to such applications and Letters Patent. INVENTOR hereby consents that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country as proof of the right of ASSIGNEE to apply for patent and other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

To be binding on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

INVENTOR:

Dated: March 24, 2015

Signature: Takeshi Kishida  
Takeshi KISHIDA

WITNESSES:

Dated: March 24, 2015

Signature: Shoji Eguchi  
Printed Name: Shoji Eguchi  
Address: c/o Micron Memory Japan, Inc., 2-1,  
Yaesu 2-chome, Chuo-ku, Tokyo, Japan